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| Dedicated PWM Input Port | | PACKAGE P VIEW) |
|--|--------------------------------|----------------------|
| Optimized for Reversible Operation of Motors | | |
| Two Input Control Lines for Reduced Microcontroller Overhead | V _{CC} [2 DIR [3 | 19 |
| Internal Current Shutdown of 5 A | V _{CC} 4 | 17 🛛 V _{CC} |
| 40 V Load Dump Rating | | |
| Integrated Fault Protection and Diagnostics | OUT1 [] 6 GND [] 7 | 15 OUT2 14 GND |
| CMOS Compatible Schmitt Trigger Inputs | | 13 STATUS1 |
| for High Noise Immunity | GND 🛛 9 | 12 GND |
| description | GNDS [10 | 11 GNDS |

description

The TPIC0107B is a PWM control intelligent H-bridge designed specifically for dc motor applications. The device provides forward, reverse, and brake modes of operation. A logic supply voltage of 5 V is internally derived from V_{CC}.

The TPIC0107B has an extremely low r_{DS(on)}, 280 mΩ typical, to minimize system power dissipation. The direction control (DIR) and PWM control (PWM) inputs greatly simplify the microcontroller overhead requirement. The PWM input can be driven from a dedicated PWM port while the DIR input is driven as a simple low speed togale.

The TPIC0107B provides protection against over-voltage, over-current, over-temperature, and cross conduction faults. Fault diagnostics can be obtained by monitoring the STATUS1 and STATUS2 terminals and the two input control lines. STATUS1 is an open-drain output suitable for wired-or connection. STATUS2 is a push-pull output that provides a latched status output. Under-voltage protection ensures that the outputs, OUT1 and OUT2, will be disabled when V_{CC} is less than the under-voltage detection voltage V_(UVCC).

The TPIC0107B is designed using TI's LinBiCMOS™ process. LinBiCMOS allows the integration of low power CMOS structures, precision bipolar cells, and low impedance DMOS transistors.

The TPIC0107B is offered in a 20-pin thermally enhanced small-outline package (DWP) and is characterized for operation over the operating case temperature of -40°C to 125°C.

| DIR | PWM | OUT1 | OUT2 MODE | | | | | | |
|-----|-----|------|-----------|---------------------------------|--|--|--|--|--|
| 0 | 0 | HS | HS | Brake, both HSDs turned on hard | | | | | |
| 0 | 1 | HS | LS | Motor turns counter clockwise | | | | | |
| 1 | 0 | HS | HS | Brake, both HSDs turned on hard | | | | | |
| 1 | 1 | LS | HS | Motor turns clockwise | | | | | |

FUNCTION TABLE



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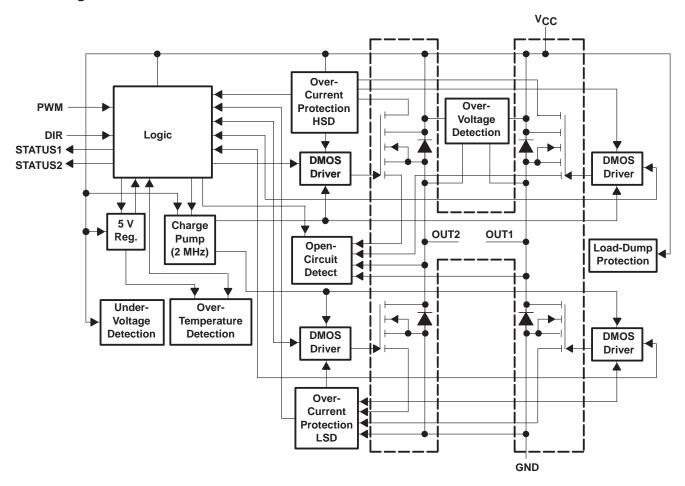
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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block diagram



Terminal Functions

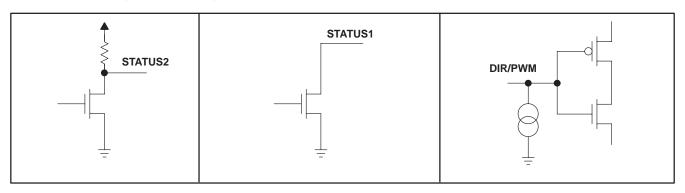
| TERM | IINAL | 1/0 | DESCRIPTION | | | | | |
|-----------------|------------------|-----|----------------------------|--|--|--|--|--|
| NAME | NO. | 1/0 | DESCRIPTION | | | | | |
| DIR | 3 | I | Direction control input | | | | | |
| GND | 7, 9, 12, 14 | I | Power ground | | | | | |
| GNDS | 1, 10, 11, 20 | I | Substrate ground | | | | | |
| OUT1 | 5, 6 | 0 | Half-H output. DMOS output | | | | | |
| OUT2 | 15, 16 | 0 | Half-H output. DMOS output | | | | | |
| PWM | 8 | 1 | PWM control input | | | | | |
| STATUS1 | 13 | 0 | Status output | | | | | |
| STATUS2 | 18 | 0 | Latched status output | | | | | |
| V _{CC} | 2, 4, 17, 19 | Ι | Supply voltage | | | | | |

NOTE: It is mandatory that all four ground terminals plus at least one substrate terminal are connected to the system ground. Use all V_{CC} and OUT terminals.



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schematics of inputs and outputs



absolute maximum ratings over operating case temperature range (unless otherwise noted)[†]

| Power supply voltage range, V _{CC} | –0.3 V to 33 V |
|---|----------------|
| Logic input voltage range, V _{IN} | –0.3 V to 7 V |
| Load dump (for 400 ms, $T_C = 25^{\circ}C$) | |
| Status output voltage range, $V_{O(status)}$ Continuous power dissipation, $T_C = 25^{\circ}C$ | –0.3 V to 7 V |
| Continuous power dissipation, $T_C = 25^{\circ}C$ | 25 W |
| Storage temperature range, T _{stg} | –55°C to 150°C |
| Maximum junction temperature, T _J | 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

| $T_A \le 25^{\circ}C$ | DERATING FACTOR | T _A = 70°C | T _A = 125°C |
|-----------------------|-----------------------------|-----------------------|------------------------|
| POWER RATING | ABOVE T _A = 25°C | POWER RATING | POWER RATING |
| 25 W | –0.2 W/°C | 16 W | |

recommended operating conditions

| | MIN | MAX | UNIT |
|--|-----|-----|------|
| Supply voltage, V _{CC} | 6 | 18 | V |
| Operating case temperature, T _C | -40 | 125 | °C |
| Switching frequency, fPWM | | 2 | kHz |



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electrical characteristics over recommended operating case temperature range and $V_{CC} = 5 V$ to 6 V (unless otherwise noted)

| | PARAMETER | | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------|---|--|-------------------------------------|------|-----|-----|-------|
| | | LSD | TJ = 25°C | | | 550 | |
| | Static drain-source on-resistance (per transistor) I(BR) = 1 A | LOD | TJ = 150°C | | | 850 | mΩ |
| rDS(on) | | HSD | $T_J = 25^{\circ}C$ | | | 600 | mΩ |
| | | | TJ = 150°C | | | 870 | 11152 |
| I(QCD) | Open circuit detection current | | | 10 | 40 | 100 | mA |
| V(UVCC(OFF)) | Under voltage detection on V _{CC} , switch off voltage | on on V _{CC} , switch off voltage | | | | 5 | V |
| V(UVCC(ON)) | Under voltage detection on V _{CC} , switch on voltage | | See Note 1 | | | 5.2 | V |
| V _(STL) | STATUS low output voltage | | I_{O} = 100 μ A, See Note 1 | | | 0.8 | V |
| V _(ST2H) | STATUS2 high output voltage | | I_{O} = 20 μ A, See Note 1 | 3 | | 5.4 | V |
| I(ST(OFF)) | STATUS output leakage current | | V _(ST) = 5 V, See Note 1 | | | 5 | μA |
| VIL | Low level logic input voltage | | | -0.3 | | 0.5 | V |
| VIH | High level logic input voltage | | | 3.6 | | 7 | V |
| ΔVI | Hysteresis of input voltage | | | 0.3 | | | V |
| Ιн | High level logic input current | | V _{IH} = 3.5 V | 2 | 10 | 50 | μΑ |

NOTE 1: The device functions according to the function table for V_{CC} between V_(UVCC) and 5 V (no parameters specified). STATUS outputs are not defined for V_{CC} less than V_(UVCC).



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electrical characteristics over recommended operating case temperature and supply voltage ranges (unless otherwise noted) (see Note 2)

| | PARAMETER | | | TEST CONDITIONS | | | MAX | UNIT |
|--------------------------|--|--------------|---|--------------------------------|------|-----|-----|--------|
| | | | Тј = 25°С | $V_{CC} = 6 V \text{ to } 9 V$ | | | 380 | |
| | | LSD | 1 J = 25°C | V _{CC} = 9 V to 18 V | | 280 | 340 | mΩ |
| | | LSD | T. 450%C | $V_{CC} = 6 V \text{ to } 9 V$ | | | 620 | 11122 |
| | Static drain-source on-resistance | | T _J = 150°C | $V_{CC} = 9 V$ to 18 V | | 400 | 560 | |
| ^r DS(on) | (per transistor) I _{BR} = 1 A | | Тј = 25°С | $V_{CC} = 6 V \text{ to } 9 V$ | | | 430 | |
| | | HSD | 1 J = 25 C | $V_{CC} = 9 V$ to 18 V | | 280 | 340 | mΩ |
| | | | T. 450%C | $V_{CC} = 6 V \text{ to } 9 V$ | | | 640 | 1112.2 |
| | | | TJ = 150°C | $V_{CC} = 9 V$ to 18 V | | 400 | 560 | |
| I(QCD) | Open circuit detection current | | | | 10 | 40 | 100 | mA |
| T _{SDS} | Static thermal shutdown temperatur | е | See Notes 3 and 4 | | 140 | | | °C |
| T _{SDD} | Dynamic thermal shutdown tempera | ature | See Notes 3 and 5 | | 160 | | | °C |
| La - Ourment elsuiteleur | Current shutdown limit | Itdown limit | | $V_{CC} = 6 V \text{ to } 9 V$ | | | 7.5 | А |
| ICS | Current shutdown limit | | $V_{CC} = 9 V$ to 18 V | | 5 | | 7.5 | A |
| I(CON) | Continuous bridge current | | $T_J = 125^{\circ}C$, Operating lifetime 10,000 hours, (see Figure 1) | | | | 3 | А |
| V _(OVCC) | Over voltage detection on V_{CC} | | | | 27 | | 36 | V |
| V(STL) | STATUS low output voltage | | I _O = 100 μA | | | | 0.8 | V |
| V(ST2H) | STATUS2 high output voltage | | I _O = 20 μA | | 3.9 | | 5.4 | V |
| I(ST(OFF)) | STATUS output leakage current | | V _(ST) = 5 V | | | | 5 | μA |
| VIL | Low level logic input voltage | | | | -0.3 | | 0.8 | V |
| VIH | High level logic input voltage | | | | 3.6 | | 7 | V |
| ΔV_{I} | Hysteresis of input voltage | | | | 0.3 | | | V |
| Iн | High level logic input current | | V _{IH} = 3.5 V | | 2 | 10 | 50 | μA |

NOTES: 2. The device functions according to the function table for V_{CC} between 18 V and V_(OVCC), but only up to a maximum supply voltage of 33 V (no parameters specified). Exposure beyond 18 V for extended periods may affect device reliability.

3. Exposure beyond absolute-maximum-rated condition of junction temperature may affect device reliability.

4. No temperature gradient between DMOS transistor and temperature sensor.

5. With temperature gradient between DMOS transistor and temperature sensor in a typical application (DMOS transistor as heat source).

switching characteristics over recommended operating case temperature and supply voltage ranges (unless otherwise noted)

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------|--|---|-----|-----|-----|------|
| + | High-side driver turn-on time | V_{22} , (1) V_{21} (1) V_{22} (1) (2) V_{23} | | | 100 | |
| ^t out(on) | Low-side driver turn-on time | V _{DS(on)} <1 V at 1 A, V _{CC} = 13.2 V | | | 100 | μs |
| CD. | Slew rate, low-to-high sinusoidal ($\delta V / \delta t$) | $V_{CC} = 13.2 \text{ V},$ $I_{O} = 1 \text{ A resistive load}$ | 1 | | 6 | V/µs |
| SR | Slew rate, high-to-low sinusoidal ($\delta V/\delta t$) | $V_{CC} = 13.2 \text{ V},$ $I_O = 1 \text{ A resistive load}$ | 1 | | 6 | v/µS |
| ^t d(QCD) | Under current spike duration to trigger open circuit detection | $V_{CC} = 5 V \text{ to } 18 V$ | 1 | | 10 | ms |
| ^t d(CS) | Delay time for over current shutdown | | 5 | 10 | 25 | μs |

thermal resistance

| | PARAMETER | MIN | MAX | UNIT |
|-----------------|--|-----|-----|------|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | | 5 | °C/W |
| $R_{\theta JC}$ | Junction-to-case thermal resistance | | 97 | °C/W |



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PARAMETER MEASUREMENT INFORMATION

Maximum continuous bridge current versus time based on 50 FITs at 100,000 hours operating life (90% confidence model)

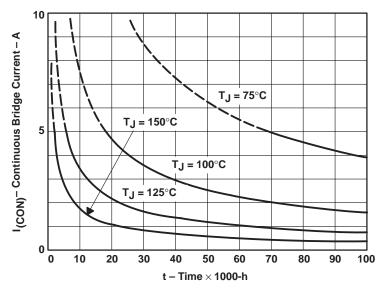


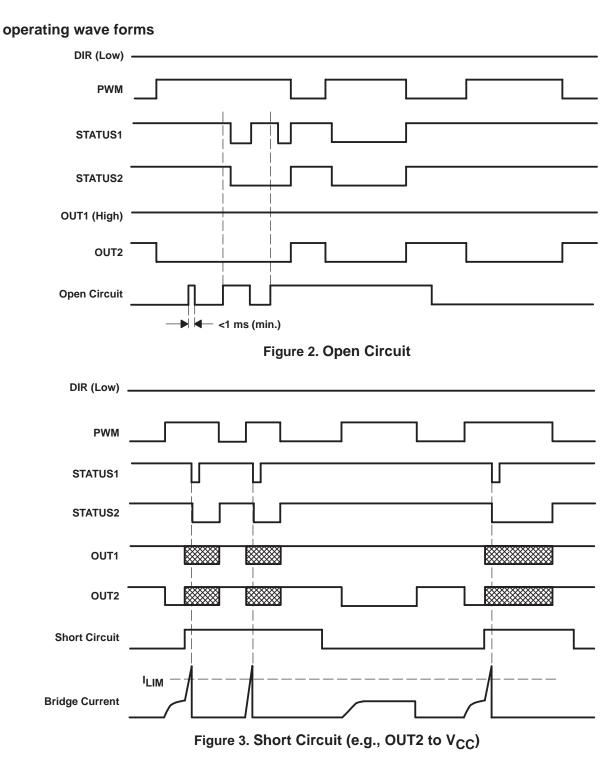
Figure 1. Electromigration Reliability Data

Example:

| Average continuous bridge current, ICON | Average junction temperature, T_J | Operating lifetime of device based on electromigration |
|---|-------------------------------------|--|
| 2 A | 125°C | >20,000 h |
| 3 A | 125°C | >10,000 h |



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PARAMETER MEASUREMENT INFORMATION



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PARAMETER MEASUREMENT INFORMATION

operating wave forms (continued)

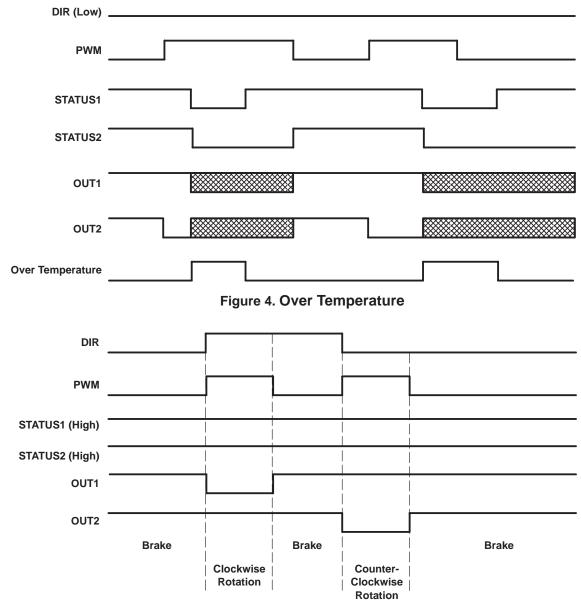


Figure 5. No Fault



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PRINCIPLES OF OPERATION

protective functions and diagnostics[†]

over current/short circuit‡

The TPIC0107B detects shorts to V_{CC} , ground, or across the load being driven, by comparing the V_{DS} voltage drop across the DMOS outputs against the threshold voltage. The DMOS outputs of the TPIC0107B will be disabled and the fault flags will be generated 10 μ s after an over-current or short-circuit fault is detected. This 10 μ s delay is long enough to serve as a de-glitch filter for high current transients, yet short enough to prevent damage to the DMOS outputs. The DMOS outputs remain latched off until either DIR or PWM input is toggled.

In cases where the outputs have a continuous short-to-ground with a current rise time faster than 0.5 A/ μ s, the over-current shutdown threshold will decrease to 3 A to reduce power dissipation. This reduction to 3 A is achieved since the DMOS outputs will not be fully enhanced when the over-current threshold is reached if the current rise time exceeds 0.5 A/ μ s. Over-current and/or short-circuit protection is provided up to V_{CC} = 16.5 V and a junction temperature of 90°C.

over temperature

The TPIC0107B disables all DMOS outputs and the fault flags will be set when $T_J \ge 140^{\circ}C$ (min.). The DMOS outputs remain latched off until either DIR or PWM input is toggled.

under voltage

The TPIC0107B disables all DMOS outputs when $V_{CC} \leq V_{(UVCC)}$. The outputs will be re-enabled when $V_{CC} \geq V_{(UVCC)}$. No fault flags are set when under-voltage lockout occurs.

over voltage

In order to protect the DMOS outputs from damage caused by excessive supply voltage, the TPIC0107B disables all outputs when $V_{CC} \ge V_{(OVCC)}$. Once $V_{CC} \le V_{(OVCC)}$, either DIR or PWM input must be toggled to re-enable the DMOS outputs.

cross conduction

Monitoring circuitry for each transistor detects whether the particular transistor is active to prevent the HSD or LSD of the corresponding half H-bridge from conducting.

open circuit

During operation, the bridge current is controlled continuously. If the bridge current is >10 mA (min.) for a period >1 ms (min.), the fault flags are set. However, the output transistors will not be disabled.

[‡] If a short circuit occurs (i.e., the over-current detection circuitry is activated) at a supply voltage higher than 16.5 V and a junction temperature higher than 90°C, damage to the device may occur.



[†] All limits mentioned are typical values unless otherwise noted.

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PRINCIPLES OF OPERATION

| FLAG | DIR | PWM | OUT1 | OUT2 | STATUS1 [†] | STATUS2 |
|--|-----|-----|------|--|----------------------|---------|
| | 0 | 0 | HS | HS | 1 | 1 |
| ormal operation0 0 1 1pen circuit between OUT1 and OUT20 0 1 1pen circuit from OUT1 to OUT2 (see Notes 7 and 8)0 1 1nort circuit from OUT1 to GND (see Notes 7 and 8)0 1 0nort circuit from OUT2 to GND (see Notes 7 and 8)0 1 1nort circuit from OUT1 to V _{CC} (see Notes 7 and 8)1 | 1 | HS | | 1 | 1 | |
| | | 0 | HS | | 1 | 1 |
| | 1 | 1 | LS | | 1 | 1 |
| | | 0 | HS | - | 1 | 1 |
| Open circuit between OUT1 and OUT2 | 0 | 1 | HS | HS 1 LS 1 HS 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 X 0 Z 0 Z 0 Z 0 | 0 | |
| • | | 0 | HS | | 1 | 1 |
| | 1 | 1 | LS | - | | 0 |
| Short circuit from OUT1 to OUT2 (see Notes 7 and 8) | 0 | 1 | X | | - | 0 |
| | 1 | 1 | Х | X | 0 | 0 |
| | 0 | 0 | Х | Х | 0 | 0 |
| Short circuit from OUT1 to GND (see Notes 7 and 8) | 1 | 0 | Х | | - | 0 |
| | 0 | 1 | Х | Х | 0 | 0 |
| | 0 | 0 | Х | | 0 | 0 |
| Short circuit from OUT2 to GND (see Notes 7 and 8) | 1 | 0 | Х | | | 0 |
| | 1 | 1 | Х | Х | 0 | 0 |
| Short circuit from OUT1 to V_{CC} (see Notes 7 and 8) | 1 | 1 | Х | Х | 0 | 0 |
| Short circuit from OUT2 to V_{CC} (see Notes 7 and 8) | 0 | 1 | Х | Х | 0 | 0 |
| | 0 | 0 | Z | Z | 0 | 0 |
| Over temperature | 0 | 1 | Z | | 0 | 0 |
| Over temperature | 1 | 0 | Z | | - | 0 |
| | 1 | 1 | Z | Z | 0 | 0 |

DIAGNOSTICS TABLE (see Note 6)

[†]When wired with a pull-up resistor

SYMBOL VALUE

0 Logic low

1 Logic high

HS High-side MOSFET conducting

LS Low-side MOSFET conducting

Z No output transistors conducting

X Voltage level undefined

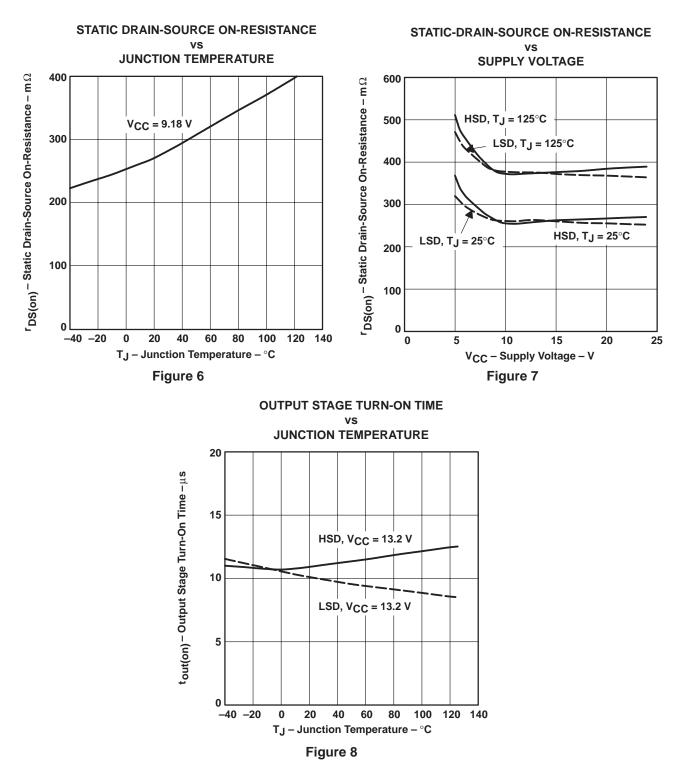
NOTES: 6. All input combinations not stated result in STATUS output = 1.

7. STATUS1 active for a minimum of 3 μ s.

8. STATUS2 active until an input is toggled.



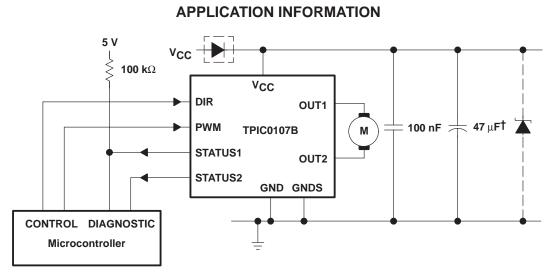
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TYPICAL CHARACTERISTICS



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[†] Necessary for isolating supply voltage or interruption (e.g., $47 \,\mu\text{F}$).

NOTE: If a STATUS output is not connected to the appropriate microcontroller input, it shall remain unconnected.

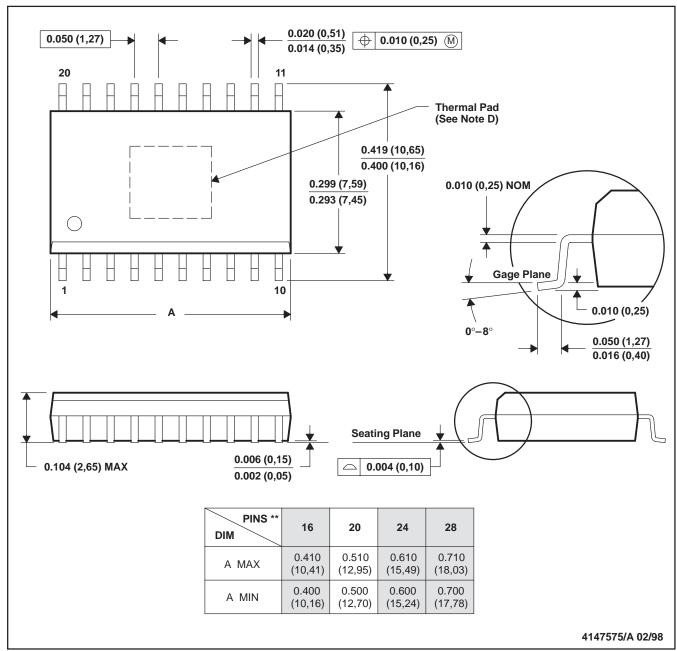


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MECHANICAL DATA

DWP (R-PDSO-G**) 20-PIN SHOWN

PowerPAD[™] PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.

PowerPAD is a trademark of Texas Instruments Incorporated.

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